

Title (en)
SPUTTERING DEVICE

Title (de)
Sputtervorrichtung

Title (fr)
DISPOSITIF DE PULVERISATION

Publication
EP 0707663 A1 19960424 (EN)

Application
EP 94921324 A 19940617

Priority
• US 9406908 W 19940617
• US 7876693 A 19930617

Abstract (en)
[origin: WO9500677A1] A sputter coating system (10) employing a vacuum chamber (1). A movable surface (2) is provided within the chamber which is adapted for mounting substrates (3) and moving them thereon. At least one magnetron sputtering device (5) is positioned at a work station adjacent to the substrate holder and adapted for sputtering at least a selected material onto the substrate. At least a second device (6) is positioned adjacent the first device for providing a plasma (11) for enhancing the plasma formed by the first device.

IPC 1-7
C23C 14/34

IPC 8 full level
C23C 14/34 (2006.01); **C23C 14/00** (2006.01); **C23C 14/35** (2006.01); **C23C 14/56** (2006.01); **H01J 37/34** (2006.01)

CPC (source: EP)
C23C 14/0047 (2013.01); **C23C 14/0078** (2013.01); **H01J 37/32192** (2013.01); **H01J 37/3233** (2013.01); **H01J 37/32678** (2013.01);
H01J 37/32862 (2013.01); **H01J 37/3405** (2013.01)

Designated contracting state (EPC)
AT BE CH DE DK ES FR GB GR IE IT LI LU MC NL PT SE

DOCDB simple family (publication)
WO 9500677 A1 19950105; EP 0707663 A1 19960424; EP 0707663 A4 19980114; JP H08511830 A 19961210

DOCDB simple family (application)
US 9406908 W 19940617; EP 94921324 A 19940617; JP 50299794 A 19940617